

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
60V	23mΩ@10V	20A
	30mΩ@4.5V	
-60V	30mΩ@-10V	-35A
	35mΩ@-4.5V	

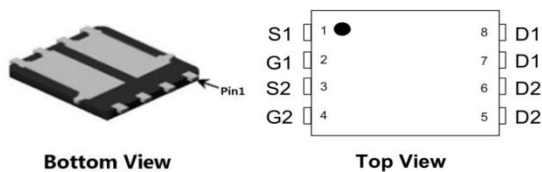
Feature

- TrenchFET Power MOSFET
- Excellent $R_{DS(on)}$ and Low Gate Charge
- Fast Switching Speed

Application

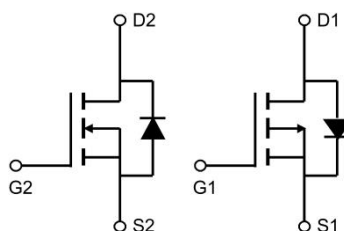
- Motor Control
- DC-DC Converters
- Power Management

Package

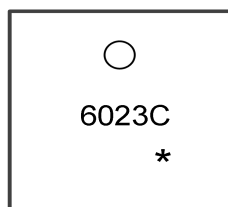


PDFN5×6-8L

Circuit diagram



Marking



6023C = Device code

***** = Month Code

**Absolute maximum ratings (Ta=25°C unless otherwise noted)**

Parameter	Symbol	Value		Unit
		N-Channel	P-Channel	
Drain-Source Voltage	V_{DS}	60	-60	V
Gate-Source Voltage	V_{GS}	± 20	± 20	V
Continuous Drain Current	I_D	20	-35	A
Power Dissipation	P_D	85	50	W
Single pulsed avalanche energy Note1	E_{AS}	40	115	mJ
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	1.47	2.5	°C/W
Junction Temperature	T_J	150		°C
Storage Temperature	T_{STG}	-55~ +150		°C

N-Channel Electrical characteristics (Ta=25 °C, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	VGS = 0V, ID = 250μA	60	-	-	V
Zero gate voltage drain current	IDSS	VDS = 80V,VGS = 0V	-	-	1	μA
Gate-body leakage current	IGSS	VGS =±20V, VDS = 0V	-	-	±0.1	μA
Gate threshold voltage	VGS(th)	VDS =VGS, ID = 250μA	1.0	1.6	2.5	V
Drain-source on-resistance	RDS(on)	VGS = 10V, ID = 2A	-	23	29	mΩ
		VGS = 4.5V, ID = 1A	-	30	40	
Dynamic characteristics						
Input Capacitance	Ciss	VDS=15V , VGS=0V , f=1MHz	-	1640	-	pF
Output Capacitance	Coss		-	120	-	
Reverse Transfer Capacitance	Crss		-	126	-	
Switching Characteristics						
Total gate charge	Qg	VDS=48V , VGS=4.5V , ID=10A	-	42	-	nC
Gate-source charge	Qgs		-	8	-	
Gate-drain charge	Qgd		-	11.5	-	
Turn-on delay time	td(on)	VDD=30V , VGS=10V , RG=3.3W, ID=10A	---	9	-	ns
Turn-on rise time	tr		---	10.5	-	
Turn-off delay time	td(off)		---	36	-	
Turn-off fall time	tf		---	5	-	
Diode Characteristics						
Diode Forward Voltage	VSD	VGS=0V , IS=1A , TJ=25℃	-	-	1.2	V

**P-Channel Electrical characteristics (T_A=25 °C, unless otherwise noted)**

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =-250μA	-60	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} = -80V,V _{GS} = 0V	-	-	-1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1	-1.7	-2.5	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} =-10V, I _D =-2A	-	30	38	mΩ
		V _{GS} =-4.5V, I _D =-1A	-	36	48	
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =-30V, V _{GS} =0V, f = 1MHz	-	2417	-	pF
Output Capacitance	C _{oss}		-	179	-	
Reverse Transfer Capacitance	C _{rss}		-	120	-	
Switching Characteristics						
Turn-on delay time	t _{d(on)}	V _{DD} =-30V, R _L = 4.7Ω V _{GEN} =-10V,R _{GEN} = 3Ω	-	9.8	-	ns
Turn-on rise time	t _r		-	6.1	-	
Turn-off delay time	t _{d(off)}		-	44	-	
Turn-off fall time	t _f		-	12.7	-	
Total gate charge	Q _g	V _{DS} =-30V, V _{GS} =-10V, I _D =-6.2A	-	46.5	-	nC
Gate-source charge	Q _{gs}		-	9.1	-	
Gate-drain charge	Q _{gd}		-	9.2	-	
Source-Drain Diode Characteristics						
Body Diode Voltage	V _{SD}	I _S =-1A, V _{GS} = 0V	-	-	-1.2	V

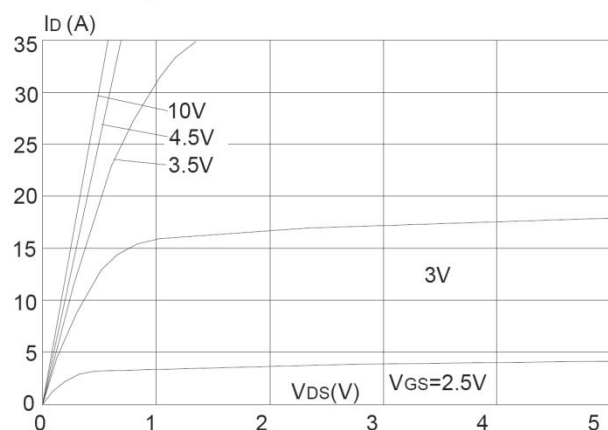
Note:

1. E_{AS} is tested at starting T_j = 25°C, V_{DD} = 30V, V_{GS} = 10V, L = 0.1mH, R_g = 25mΩ;

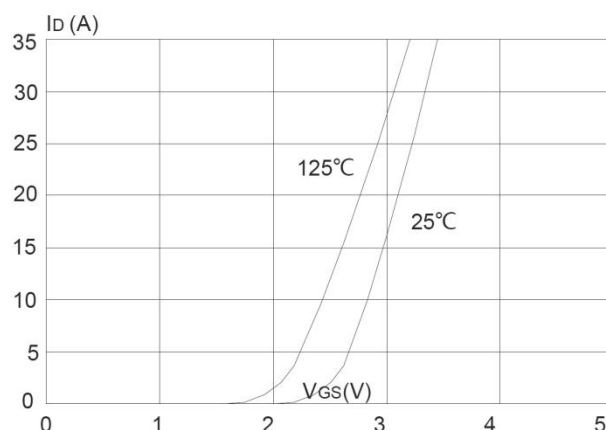


N-Channel Typical Characteristics

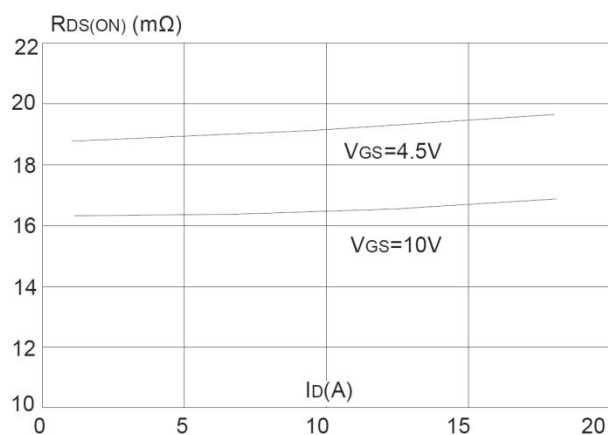
Output Characteristics



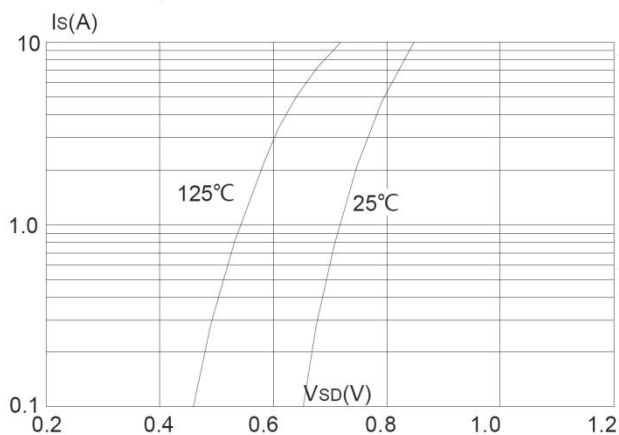
Typical Transfer Characteristics



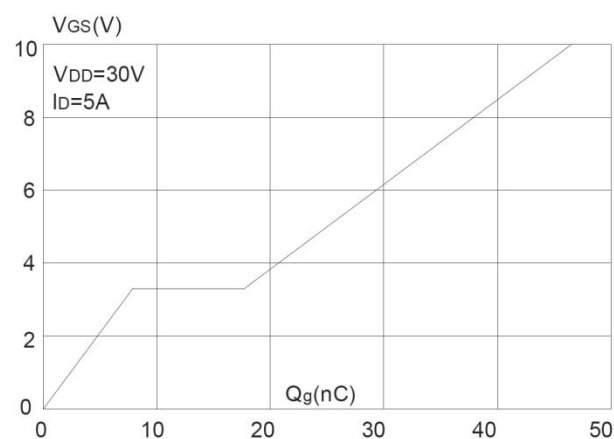
On-resistance vs. Drain Current



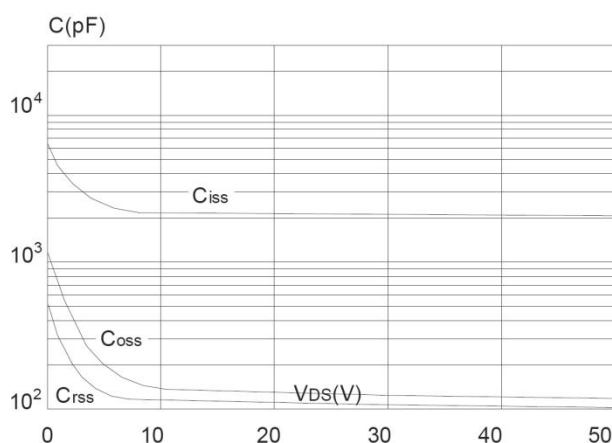
Body Diode Characteristics



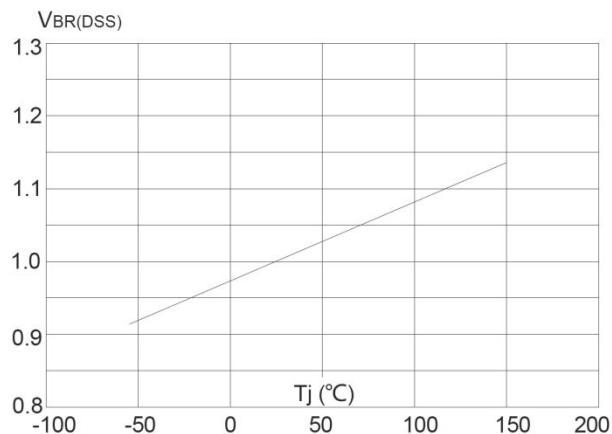
Gate Charge Characteristics



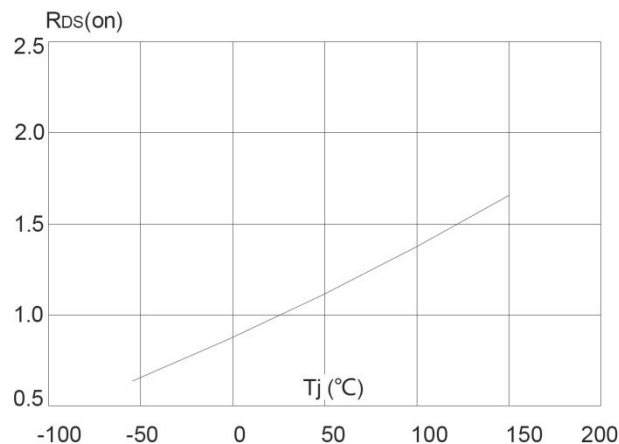
Capacitance Characteristics



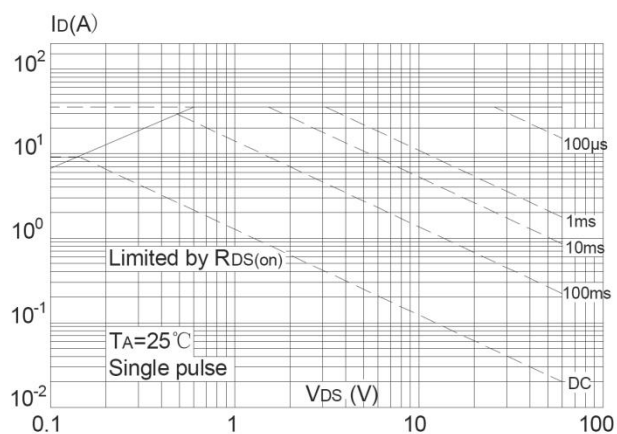
Normalized Breakdown Voltage vs. Junction Temperature



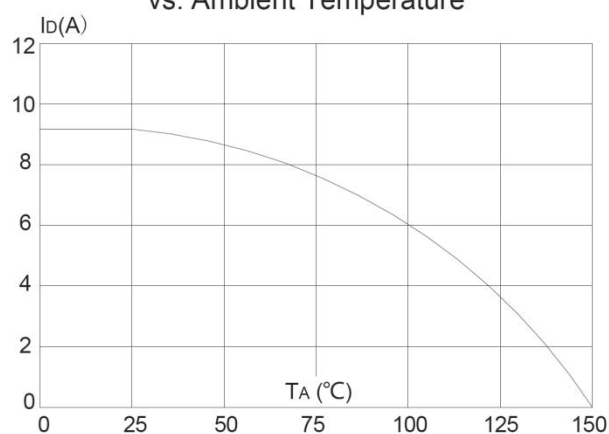
Normalized on Resistance vs. Junction Temperature



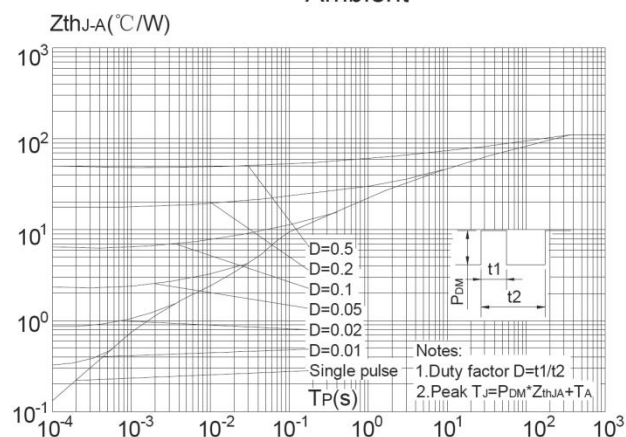
Maximum Safe Operating Area



Maximum Continuous Drain Current vs. Ambient Temperature



Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



P-Channel Typical Characteristics

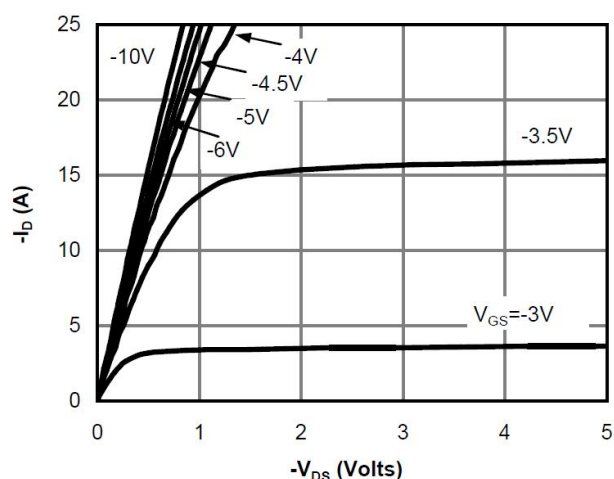


Fig 1: On-Region Characteristics

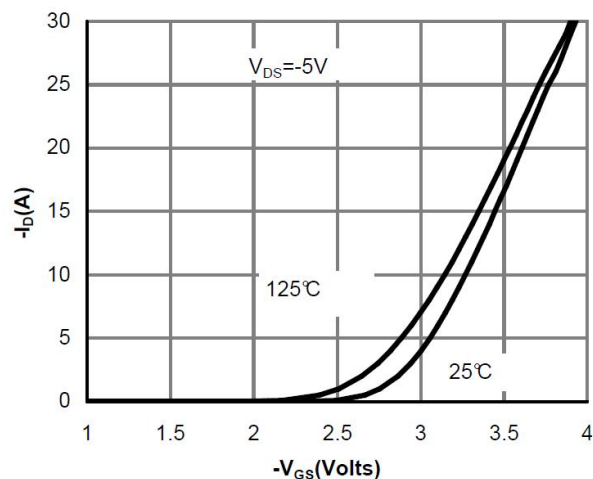


Figure 2: Transfer Characteristics

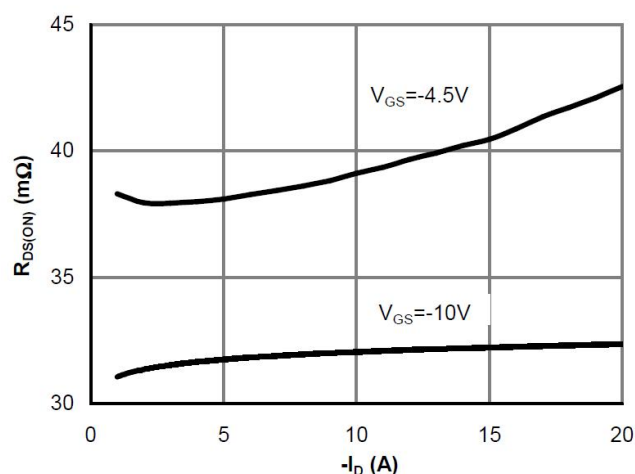


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

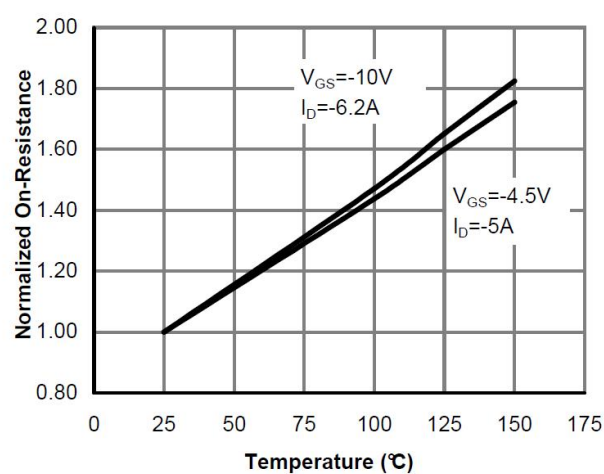


Figure 4: On-Resistance vs. Junction Temperature

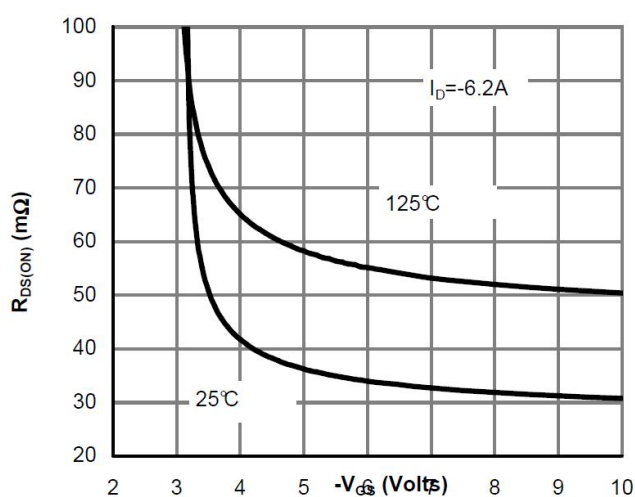


Figure 5: On-Resistance vs. Gate-Source Voltage

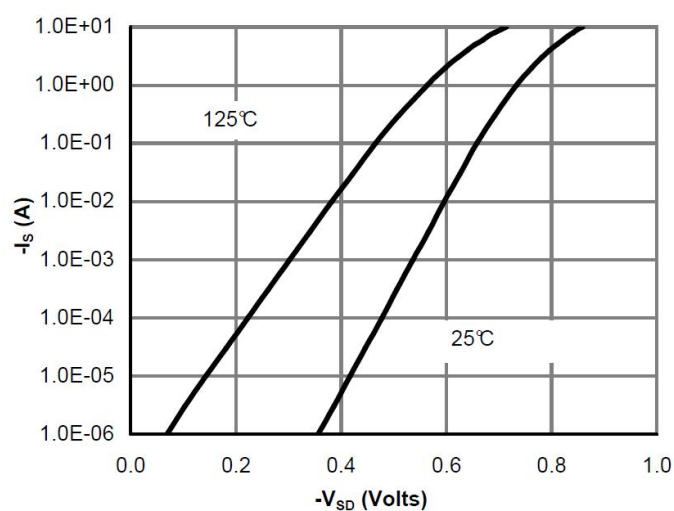


Figure 6: Body-Diode Characteristics

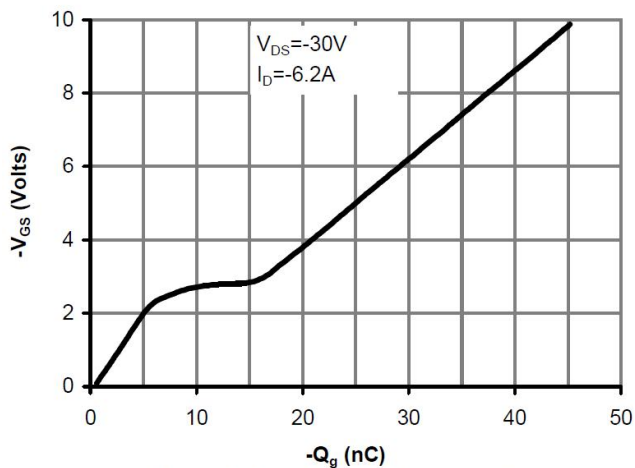


Figure 7: Gate-Charge Characteristics

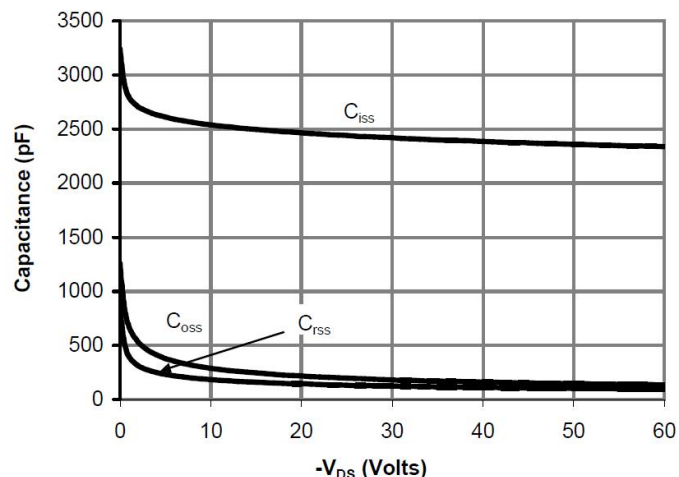


Figure 8: Capacitance Characteristics

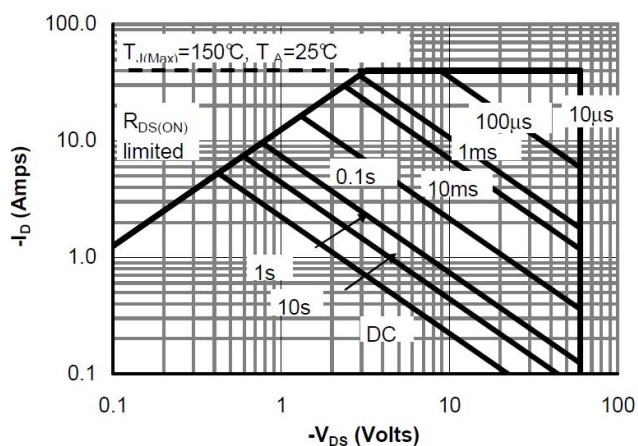


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

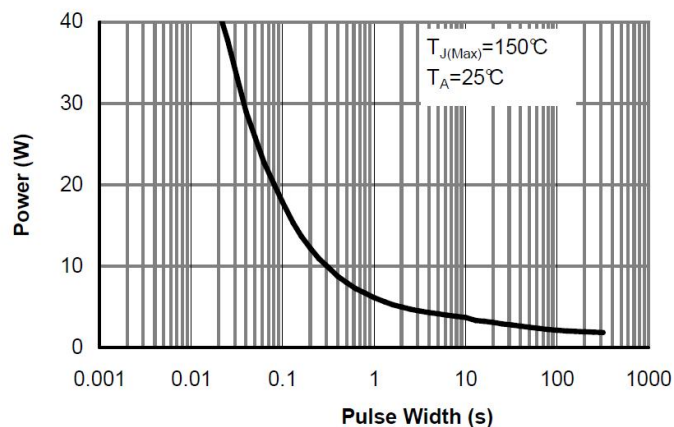


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

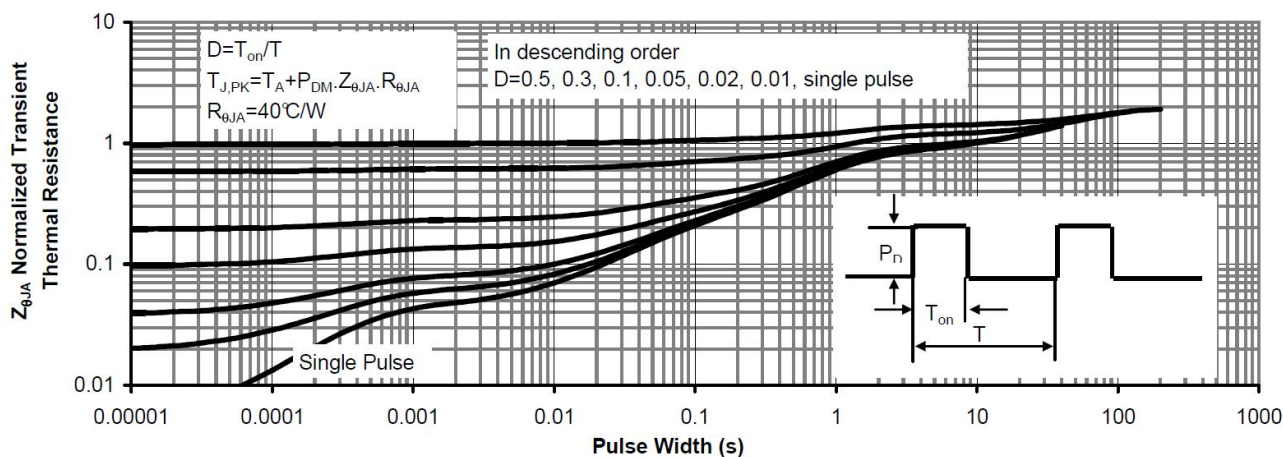
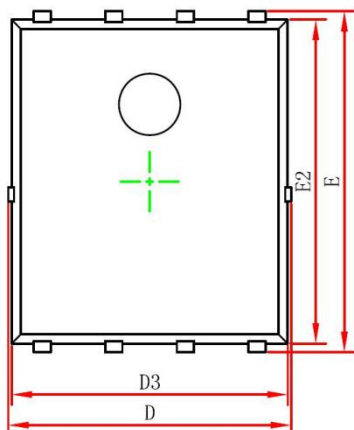
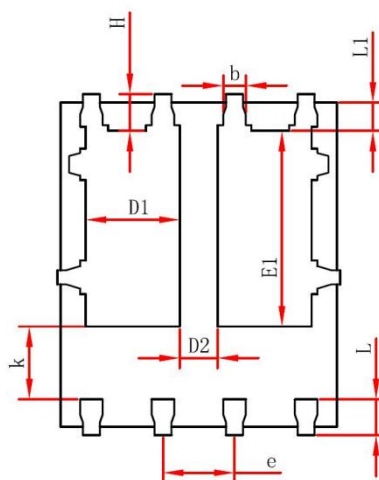
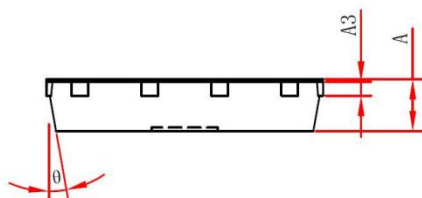


Figure 11: Normalized Maximum Transient Thermal Impedance



PDFN5X6-8L Package Information

Top View
[顶视图]Bottom View
[背视图]Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.254 REF.		0.010 REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	1.470	1.870	0.058	0.074
D2	0.470	0.870	0.019	0.034
E1	3.375	3.575	0.133	0.141
D3	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270 TYP.		0.050 TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°



制 修 订 记 录					
文件版本	制修日期	修订页次	修订人	变更内容	
Ver-1.0	2023/3/1		覃源	新建规格书	
批准		审核		编制	
日期		日期		日期	